## ABSTRACT

In the present invention, an insulating film adhesive material is attached onto the wirings in the form of a tent so that an empty space communicating with a vent hole is provided. Use of this chip-supporting substrate makes it possible to produce small-sized semiconductor packages preventive of package cracking and having a high reliability, because the function of the vent hole is not damaged and also gases and water vapor which are generated from the insulating film adhesive material at the time of reflowing can be driven off surely outside the package.